Applications

The TDEX6015/TH/12/G is a compact high-performance extruded fan heat sink assembly designed for use with thermoelectric (Peltier effect) coolers of up to 30mm x 30mm footprint and up to 22W Qmax. It would be equally suitable for other semiconductor applications requiring high performance within a compact footprint.

- L: 60 W: 60 D: 47mm Mass: 170g
- 12V (1.8W) fan
- 6035-T5 black anodized heat sink
- Machined thermal interface
- 2 x M3 fixing holes
- Finger guard included
- 0.50 deg C/W